LN2162C13TR

Surface Mounting Chip LED

GW Bi-Color Type

■ Absolute Maximum Ratings $T_a = 25$ °C

• Rec

Parameter	Symbol	Rating	Unit	
Power dissipation	P_{D}	45	mW	
Forward current	I_{F}	15	mA	
Pulse forward current *	I_{FP}	60	mA	
Reverse voltage	V _R	3	V	
Operating ambient temperature	T _{opr}	-25 to +80	°C	
Storage temperature	T _{stg}	-30 to +85	°C	

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

• Green

Parameter	Symbol	Rating	Unit	
Power dissipation	P_{D}	45	mW	
Forward current	I_{F}	15	mA	
Pulse forward current *	I _{FP}	60	mA	
Reverse voltage	V_R	4	V	
Operating ambient temperature	T _{opr}	-25 to +80	°C	
Storage temperature	T _{stg}	-30 to +85	°C	

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Electro-Optical Characteristics $T_a = 25$ °C

• Red

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity	I _O	it for Miss	0.65	1.8		mcd
Forward current	I_{F}	112. 1/1/4		10		mA
Forward voltage	V _F	$I_F = 10 \text{ mA}$		2.0	2.8	V
Peak emission wavelength	$\lambda_{ m P}$	$I_F = 10 \text{ mA}$		650		nm
Spectral half band width	Δλ	$I_F = 10 \text{ mA}$		40		nm
Reverse current	I_R	$V_R = 3 V$			10	μΑ

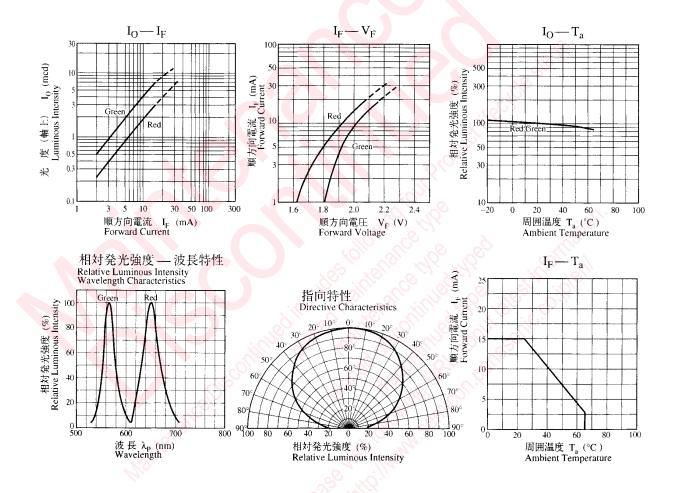
■ Lighting Color / Lens Color

- Red / Clear
- Green / Clear

■ Electro-Optical Characteristics (Continued) $T_a = 25$ °C

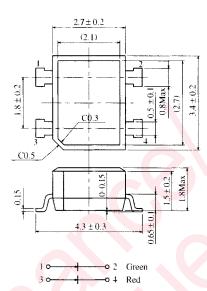
• Green

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity	I _O		1.5	4.0		mcd
Forward current	I_F			10		mA
Forward voltage	V _F	$I_F = 10 \text{ mA}$		2.05	2.8	V
Peak emission wavelength	$\lambda_{ m P}$	$I_F = 10 \text{ mA}$		565		nm
Spectral half band width	Δλ	$I_F = 10 \text{ mA}$		30		nm
Reverse current	I_R	$V_R = 4 V$			10	μΑ



2 SHD00439AEK

■ Package (Unit: mm)



- Pin name
 - 1, 3: Anode
 - 2, 4: Cathode

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